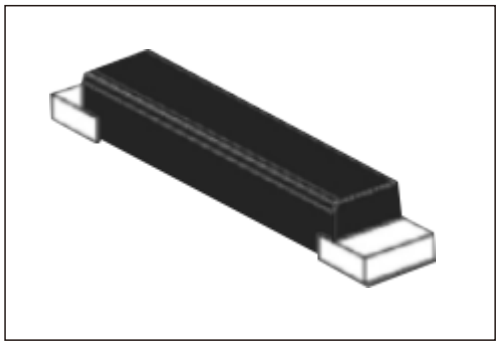
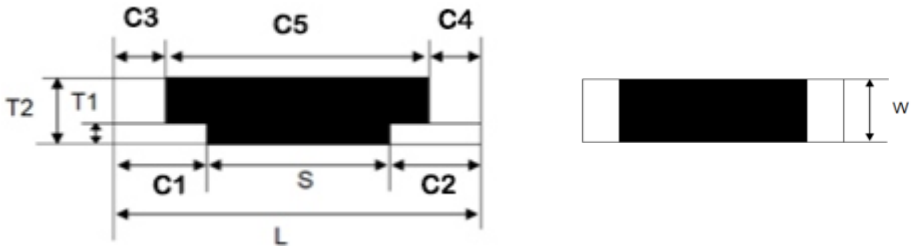


Features

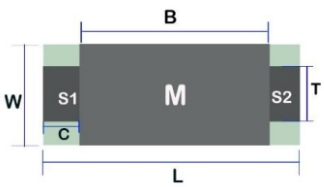
-The alloy plate is tinned and has good welding performance
-High reliability,high overload capacity,rated current 10-40A
-ROHS compliant and halogen-free
-Wide operating temperature range and non-inductive design

Dimensions



Type	Size (mm)	L	W	T1	T2	S	C1/C2	C3/C4	C5
LJR	8215	8.2±0.20	1.5±0.20	0.5±0.15	1.0±0.15	5.8±0.5	1.0±0.4	0.8±0.4	6.55±0.4

Recommend Land Pattern



Type	Size (mm)	L	W	B	C	T
LJR	8215	9.8	2.5	6.4	1.5	1.5

Note: The "M" section indicates the location of the plastic insulation layer; the "S1" and "S2" sections indicate the positions of the circuit board pads.

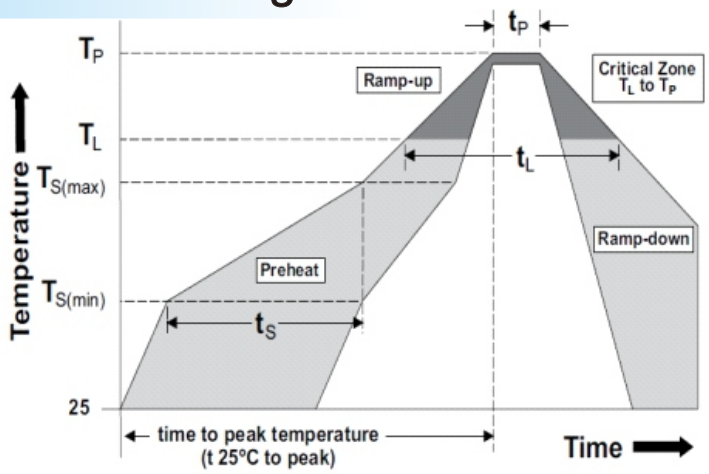
Ordering Information

Example

LJR	8215	150A	0mΩ	E	F
(1)	(2)	(3)	(4)	(5)	(6)
Type	Size	Current Rated	Reisitance	Package	Material

(1)Type:LJR
(2)Size:8215
(3)Current Rated:20A
(4)Reisitance:R000=0 mΩ
(5)Package:E= Embossed taping
(6)Material:F =Fe、C=Cu

IR Reflow-Soldering Profile



Reflow Condition		Pb – Free assembly
Pre heat	- Temperature Min (Ts(min))	150℃
	- Temperature Max (Ts(max))	200℃
	- Time (Min to Max) (ts)	60 – 180 secs
Average ramp up rate (Liquidus Temp (TL) to peak		5℃/second max
Ts(max) to TL - Ramp-up Rate		5℃/second max
- Temperature (TL) (Liquidus)		217℃
- Time (tL)		60 – 150 seconds
Peak Temperature (TP)		260℃
Time within 5℃ of actual peak Temperature (tp)		10 – 30 seconds
Ramp-down Rate		6℃/second max
Time 25℃ to peak Temperature (TP)		8 minutes Max.
Wave Soldering		260℃ 10 seconds max.
Hand Soldering		350℃, 5 seconds max.

Performance

Item	Requirement	Test Method
Working Current	The component can withstand an operating current of no less than 10 A.	Rated 20A
Internal Resistance	Resistance value at both ends of the test element	<10mΩ
Adhesion strength of the insulating layer	Use your thumb or an eraser to test the insulation layer (both the bottom and top surfaces). Apply a force of 3.0 ± 0 KGF and rub the surface 10 times; the adhesive should not peel off.	The adhesive detachment area is less than 10%.
Solderability	Temperature of Solder: 245±5℃ Dipping time:3±1s	Solder coverage over 95%
SMT Reflow Soldering Test	Reflow furnace temperature: 180℃~250℃ Reflow soldering time: 60 seconds	The Shanghai copper price is good.
High Temperature Exposure (Storage)	Put tested resistor in chamber under temperature 70℃ for 15%,96hours Then leaving the tested resistor in room temperature for 60 minutes , and measure its resistance variance rate.	The two tin-coated ends do not oxidize.
Low Temperature Exposure (Storage)	Put the tested resistor in chamber under temperature -20℃ 15%,for 96 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate.	The two tin-coated ends do not oxidize.
Low Temperature Exposure (Storage)	Put the tested resistor in chamber under temperature 40±2℃,90~95%, for 96 hours.Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate.	The two tin-coated ends do not oxidize.